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February 2015

FPF2487 Dual Channel Over-Voltage Protection Load Switch

Features

Dual Channel Power Switch (V_{BUS} and V_{IF})

■ Surge Protection under IEC 61000-4-5

V_{BUS}: ±100 VV_{IF}: ±40 V

Input Voltage Range

V_{BUS}: 2.5 V ~ 23 V
 V_{IF}: 3.1 V ~ 5.5 V

Max. Continuous Current Capability

V_{BUS}: 2.5 AV_{IF}: 6 A

Ultra Low On-Resistance

V_{BUS}: Typ. 33 mΩ
 V_{IF}: Typ. 11 mΩ

Over-Voltage Protection

- V_{BUS} : 5.95 V ± 50 mV - V_{IF} : 5.25 V ± 250 mV

LDO Output based V_{BUS} DET for V_{BUS} Detection

Active Low Control for V_{BUS} Path

OTG Functionality on V_{BUS} Path

Conditional Active High Control for V_{IF} Path

Reverse-Current Blocking for V_{IF} Path

Description

The FPF2487 features a 2-channel power switch, which offers surge protection and Over-Voltage Protection (OVP), to protect downstream components and enhancing overall system robustness.

Channel one (V_{BUS}) is an active-low, 28 V/2.5 A rated, power MOSFET switch with an internal clamp supporting ± 100 V surge protection, highly accurate fixed OVP at 5.95 V (± 50 mV), and OTG functionality. Channel two (V_{IF}) is a conditional active-high, 6 V/6 A rated, power MOSFET switch with an integrated TVS supporting ± 40 V surge protection and fixed OVP at 5.25 V (± 250 mV). V_{IF} also provides Reverse Current Blocking (RCB) during its OFF state to minimize leakage current.

 V_{BUS_DET} is paired with always ON LDO to power downstream devices even with V_{BUS} is greater than 2.5 V, even when disabled through the ONB pin. This provides power sequence control or a host controlled configuration in system.

The FPF2487 is available in a 15-bump, 1.6 mm x 2.2 mm Wafer-Level Chip-Scale Package (WLCSP) with 0.4 mm pitch.

Related Resources

http://www.fairchildsemi.com/

Applications

- Mobile Handsets and Tablets
- Wearable Devices

Ordering Information

Part Number	Operating Temperature Range	Top Mark	Package	Packing Method
FPF2487UCX	-40°C – +85°C	GX	15-Ball, 0.4 mm Pitch WLCSP	Tape & Reel

Application Diagram

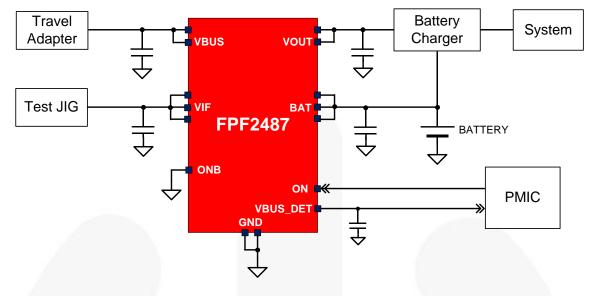


Figure 1. Typical Application

Block Diagram

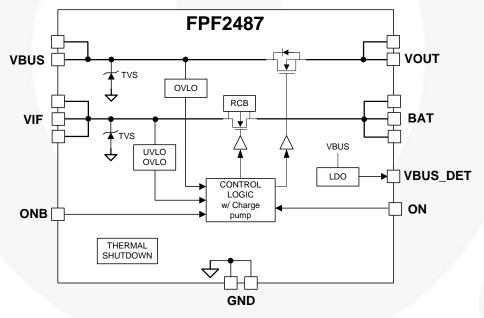
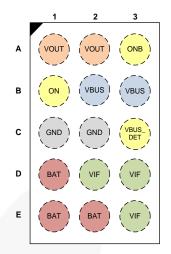


Figure 2. Functional Block Diagram

Pin Configuration



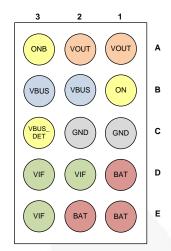


Figure 3. Pin Configuration (Top View)

Figure 4. Pin Configuration (Bottom View)

Pin Definitions

Name	Bump	Туре	Description	
V _{BUS}	B2, B3	Input/Supply	Switch Input and Device Supply	
V _{OUT}	A1, A2	Output	Switch Output to Load	
V_{IF}	D2, D3, E3	Input/Supply	Switch Input and Device Supply	
BAT	D1, E1, E2	Output	Switch Output to Battery	
V_{BUS_DET}	C3	Output	Regulated Output according to V _{BUS}	
ON	B1	Input	Active HIGH: V _{IF} path only and when BAT is valid prior to V _{IF}	
ONB	А3	Input	Active LOW: V _{BUS} path only	
GND	C1, C2	GND	Ground	

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter			Min.	Max.	Unit
V _{BUS}	V _{BUS} to GND & V _{BUS} to V _{OUT} =GND or Float			-0.3	29.0	V
V _{IF}	V _{IF} to GND			-2 ⁽¹⁾	6	V
V _{OUT}	V _{OUT} to GND			-0.3	V _{IN} + 0.3	V
BAT	BAT to GND			-0.3	V _{IF} + 0.3	V
V _{BUS_DET}	V _{BUS_DET} to GND				8	V
V _{ON(B)}	ONB or ON to GND				6	V
	Continuous V _{BUS} Current				2.5	Α
I _{IN_VBUS}	Peak V _{BUS} Current (5 ms)				5	Α
. /	Continuous V _{IF} Current				6	Α
I _{IN_VIF}	Peak V _{IF} Current (5 ms)				12	Α
I _{IN_VBUS_DET}	Continuous V _{BUS_DET} Current				1	mA
t _{PD}	Total Power Dissipation at T _A =25°C				1.54	W
T _{STG}	Storage Temperature Range				+150	°C
TJ	Maximum Junction Temperature				+150	°C
TL	Lead Temperature (Soldering, 10 Seconds)				+260	°C
Θ_{JA}	Thermal Resistance, Junction	n-to-Ambient ⁽²⁾ (1-in. ² Pad	of 2-oz. Copper)		81 ⁽²⁾	°C/W
	Electrostatic Discharge Capability IEC 610 Level E Human ANSI/E 001-20 Charge	IEC 61000-4-2 System Level ESD	Air Discharge	15		
			Contact Discharge	8		İ
ESD		Human Body Model, ANSI/ESDA/JEDEC JS- 001-2012	All Pins	2		kV
		Charged Device Model, JESD22-C101	All Pins	1		
Surgo		IEC 61000-4-5,	V _{BUS}	±100	į.	V
Surge		Surge Protection	V _{IF}	±40		

Notes:

- 1. Pulsed, 50 ms maximum non-repetitive.
- 2. Measured using 2S2P JEDEC std. PCB.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	l Parameter		Max.	Unit
V _{BUS}	Supply Voltage, V _{BUS}	2.5	23.0	V
V_{IF}	Supply Voltage, V _{IF}	3.1	5.5	V
C _{IN} / C _{OUT}	Input and Output Capacitance			μF
C _{VBUS_DET}	Output Capacitance	0.47		μF
T _A	Operating Temperature	-40	+85	°C

Electrical Characteristics

Unless otherwise noted, V_{BUS} =2.5 to 23 V, V_{IF} =3.1 to 5.5 V, T_{A} =-40 to 85°C; Typical values are at V_{BUS} =5 V, $I_{IN} \le 2$ A, V_{IF} =4 V, C_{IN} =0.1 μF and T_{A} =25°C.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Basic Oper	ation					
1	Input Quiescent Current	V _{BUS} =5 V, ONB=0 V, V _{BUS_DET} =Floating		160	250	μΑ
ΙQ		V _{IF} =4 V		100	150	μΑ
I.e. a	OVLO Supply Current	V _{BUS} =12 V, V _{OUT} =0 V, V _{BUS_DET} =Floating		150	205	μΑ
I _{IN_Q}		V _{IF} =5.5 V, BAT=0 V		100	180	μΑ
T_{SDN}	Thermal Shutdown ⁽³⁾			140		°C
T _{SDN_HYS}	Thermal Shutdown Hysteresis ⁽³⁾			20		°C
V _{BUS} to V _O	Switch					
V _{BUS_CLAMP}	Input Clamping Voltage	I _{IN} =10 mA		35		V
V	Over Veltage Trip Level	V _{BUS} Rising, T _A =-40 to 85°C	5.90	5.95	6.00	V
V _{BUS_OVLO}	Over-Voltage Trip Level	V _{BUS} Falling, T _A =-40 to 85°C	5.8			V
	0.0	V _{BUS} =5 V, I _{OUT} =1 A, T _A =25°C		33	39	mΩ
R _{ON_VBUS}	On-Resistance	V _{BUS} =9 V, I _{OUT} =1 A, T _A =25°C		33	39	mΩ
t _{DEB_VBUS}	Debounce Time	Time from $V_{BUS_MIN} < V_{BUS} < V_{BUS_OVLO}$ to V_{OUT} =0.1 × V_{BUS}		15		ms
t _{START_VBUS}	Soft-Start Time	Time from V _{BUS} =V _{BUS} MIN to 0.1 × V _{BUS} DET		30		ms
t _{ON_VBUS}	Switch Turn-On Time	$R_L{=}100~\Omega,~C_L{=}22~\mu\text{F},~V_{OUT}~from~0.1~\times~V_{BUS}~to~0.9~\times~V_{BUS}$		3		ms
toff_vbus	Switch Turn-Off Time	R_L =100 Ω , No C_L , $V_{BUS} > V_{BUS_OVLO}$ to V_{OUT} =0.8 \times V_{BUS}			150	ns
V _{IF} to BAT	Switch		A			
VIF_CLAMP	Input Clamping Voltage	I _{IN} =10 mA	A	6.4		V
		V _{IF} Rising, T _A =-40 to 85°C		2.85	3.05	V
V_{IF_UVLO}	Under-Voltage Trip Level	V _{IF} Falling, T _A =-40 to 85°C		2.7		V
V	Over-Voltage Trip Level	V _{IF} Rising, T _A =-40 to 85°C	5.00	5.25	5.50	V
V _{IF_OVLO}		V _{IF} Falling, T _A =-40 to 85°C	4.8	, , ,		V
R _{ON_VIF}	On-Resistance	V _{IF} =3.1 V, I _{OUT} =1 A, T _A =25°C		10	15	mΩ
I _{RCB}	Reverse Current	V _{IF} =0 V, BAT=4.4 V		3	7	μΑ
t _{DEB_VIF}	Debounce Time	Time from $V_{IF_UVLO} < V_{IF} < V_{IF_OVLO}$ to BAT=0.1 x V_{IF}		15		ms
t _{QUAL_VIF}	Qualification Tim	BAT > VIH_BAT First, Time from ON > VIH_ON(B) to BAT Voltage Increase		2		ms
t _{ON_VIF}	Switch Turn-On Time	$R_L {=} 100~\Omega,~C_L {=} 22~\mu F,~V_{OUT}~from~0.1~\times~V_{IF}~to~0.9~\times~V_{IF}$		2		ms
t _{OFF_VIF}	Switch Turn-Off Time	R_L =100 Ω, No C_L , V_{IN} > V_{OVLO} to V_{OUT} =0.8 × V_{IF}			150	ns

Note:

3. Guaranteed by characterization and design.

Continued on the following page...

Electrical Characteristics (Continued)

Unless otherwise noted, V_{BUS} =2.5 to 23 V, V_{IF} =3.1 to 5.5 V, T_{A} =-40 to 85°C; Typical values are at V_{BUS} =5 V, $I_{IN} \le 2$ A, V_{IF} =4 V, C_{IN} =0.1 μF and T_{A} =25°C.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
V _{BUS_DET}				•	•	•
	V _{BUS_DET} Output Voltage	V_{BUS} =6.5 V, I_{BUS_DET} =0 mA, T_A =25°C	6.0		6.5	V
M		V_{BUS} =15 V, I_{BUS_DET} =0 mA, T_A =25°C	6.0	7.0	7.9	V
V _{BUS_DET}		V_{BUS} =6.5 V, I_{BUS_DET} =1 mA, T_A =25°C	6.0	6.3	6.5	V
		V_{BUS} =15 V, I_{BUS_DET} =1 mA, T_A =25°C	6.0	7.0	7.9	V
Digital Signals						
V _{IH_ON(B)}	Enable HIGH Voltage	V _{BUS} , V _{IF} Operating Range	1.2			V
V _{IL_ON(B)}	Enable LOW Voltage	V _{BUS} , V _{IF} Operating Range			0.5	V
V _{IH_BAT}	BAT Presence HIGH Voltage	BAT Rising	2.5			V
V _{IL_BAT}	BAT Presence LOW Voltage	BAT Falling			1.7	V
IVBUS_DET_LEAK	V _{BUS_DET} Leakage Current	V _{VBUS_DET} =5 V, V _{BUS} =0 V			1	μΑ
ON(B)_Leak	ON(B) Leakage Current	V _{BUS} =5 V, V _{OUT} =Float			1	μΑ

Timing Diagrams

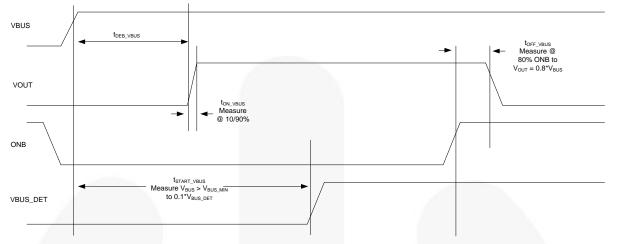


Figure 5. Timing for V_{BUS} Power Up/Down and Normal Operation

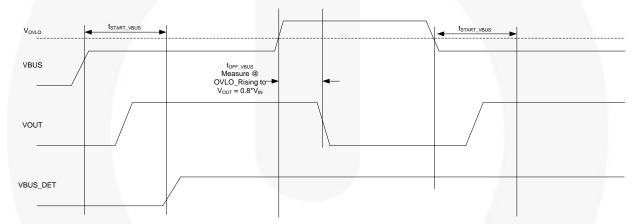


Figure 6. Timing for V_{BUS} OVLO Operation (ONB=LOW)

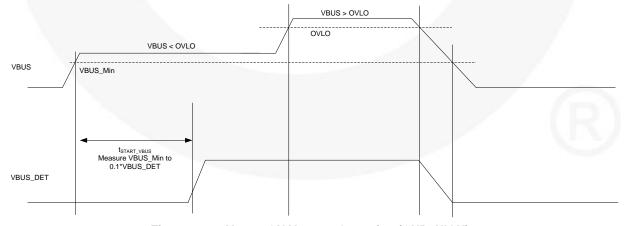


Figure 7. Always ON V_{BUS_DET} Operation (ONB=HIGH)

Timing Diagrams (Continued)

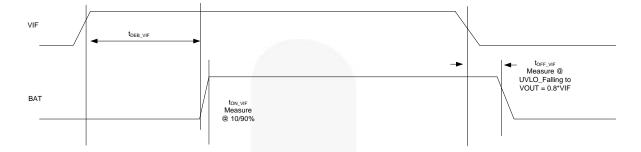


Figure 8. Timing for V_{IF} Power Up/Down and Normal Operation (ON=Don't Care)

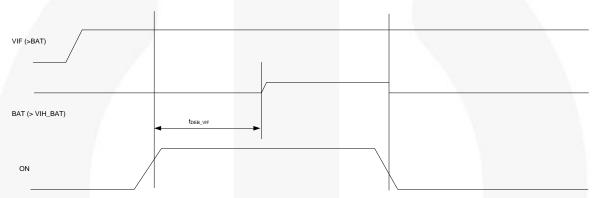


Figure 9. Timing for V_{IF} Power Up/Down and Normal Operation with ON Pin

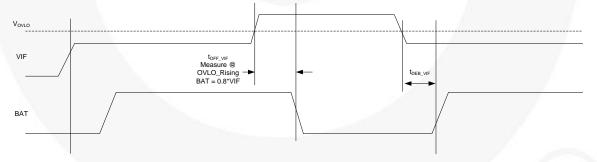


Figure 10. Timing for V_{IF} OVLO Operation (ON=Don't Care)

VIF Turn-On Qualification State Diagram

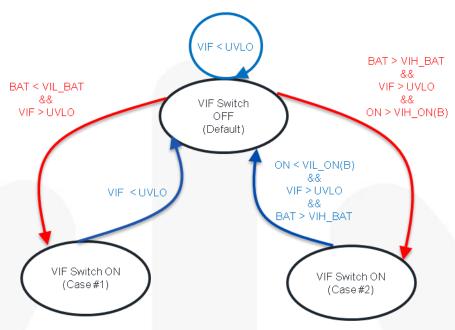


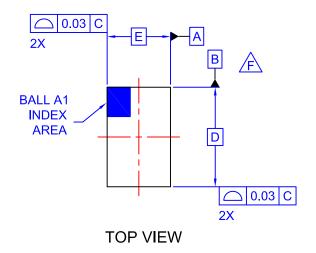
Figure 11. V_{IF} Turn-On Qualification State Diagram

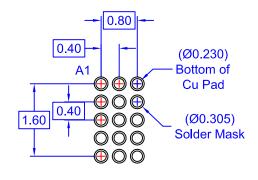
Notes:

- 4. Case #1 is reflecting removable battery system without ON signal.
- 5. Case #2 is reflecting embedded battery system with ON signal.

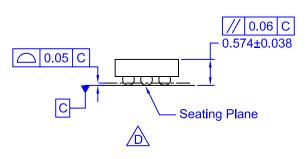
Product-Specific Package Dimensions

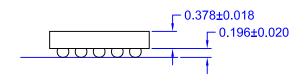
D	D E		Υ	
2200 μm ±30 μm	1600 μm ±30 μm	400 μm ±18 μm	300 μm ±18 μm	



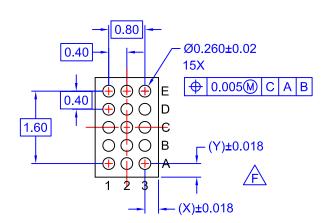


RECOMMENDED LAND PATTERN (NSMD TYPE)





SIDE VIEWS



BOTTOM VIEW

NOTES

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCE PER ASMEY14.5M, 2009.
- D. DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E. PACKAGE NOMINAL HEIGHT IS 574 ± 38 MICRONS (536-612 MICRONS).
- F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.
- G. DRAWING FILNAME: MKT-UC015AC REV2.



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